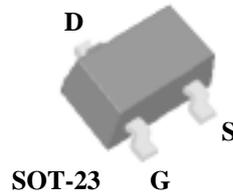


## AP2318GEN

- ▼ Capable of 2.5V gate drive
- ▼ Small outline package
- ▼ RoHS Compliant

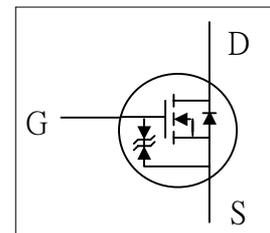


$BV_{DSS}$	30V
$R_{DS(ON)}$	720m $\Omega$
$I_D$	1A

### Description

Advanced Power MOSFETs utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The SOT-23 package is universally used for all commercial-industrial applications.



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 16$	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current <sup>3</sup> , $V_{GS} @ 4.5\text{V}$	1	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current <sup>3</sup> , $V_{GS} @ 4.5\text{V}$	0.8	A
$I_{DM}$	Pulsed Drain Current <sup>1,2</sup>	2	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation	1.38	W
	Linear Derating Factor	0.01	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Thermal Resistance Junction-ambient <sup>3</sup> Max.	90	$^\circ\text{C}/\text{W}$

Electrical Characteristics @  $T_j=25^{\circ}\text{C}$  (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$	-	0.04	-	$V/^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4V, I_D=500\text{mA}$	-	-	720	$\text{m}\Omega$
		$V_{GS}=2.5V, I_D=200\text{mA}$	-	-	1200	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	-	1.3	V
$g_{fs}$	Forward Transconductance	$V_{DS}=4V, I_D=500\text{mA}$	-	725	-	$\text{mS}$
$I_{DSS}$	Drain-Source Leakage Current ( $T_j=25^{\circ}\text{C}$ )	$V_{DS}=30V, V_{GS}=0V$	-	-	-1	$\mu A$
	Drain-Source Leakage Current ( $T_j=70^{\circ}\text{C}$ )	$V_{DS}=24V, V_{GS}=0V$	-	-	-25	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=\pm 16V$	-	-	$\pm 30$	$\mu A$
$Q_g$	Total Gate Charge <sup>2</sup>	$I_D=1A$	-	1.1	1.8	$\text{nC}$
$Q_{gs}$	Gate-Source Charge	$V_{DS}=25V$	-	0.4	-	$\text{nC}$
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	0.4	-	$\text{nC}$
$t_{d(on)}$	Turn-on Delay Time <sup>2</sup>	$V_{DS}=15V$	-	17	-	$\text{ns}$
$t_r$	Rise Time	$I_D=1A$	-	44	-	$\text{ns}$
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega, V_{GS}=5V$	-	45	-	$\text{ns}$
$t_f$	Fall Time	$R_D=15\Omega$	-	55	-	$\text{ns}$
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	30	48	$\text{pF}$
$C_{oss}$	Output Capacitance	$V_{DS}=25V$	-	12	-	$\text{pF}$
$C_{rss}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	11	-	$\text{pF}$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=1A, V_{GS}=0V$	-	-	1.3	V

## Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Surface mounted on  $1\text{ in}^2$  copper pad of FR4 board;  $270^{\circ}\text{C}/W$  when mounted on min. copper pad.